

PRODUCT/PROCESS CHANGE NOTIFICATION PCN 11442 – Additional information

SG8E (Singapore) additional source for STM8L052 32k/64k - STM8L15x 32k/64k products

MDG - Microcontrollers Division (MCD)

The standard marking is:



WX code indicates the diffusion traceability plant code.

Please refer to the DataSheet for marking details.

The marking is changing as follows:

	Existing	Additional		
WX code	WX code Fab		Fab	
VG	ST Rousset 8"(France)	VC	ST SG8 8" (Singapore)	

How to order samples?

For all samples request linked to this PCN, please:

- place a <u>Non-standard</u> sample order (choose Sample Non Std Type from pull down menu)
- insert the PCN number "PCN11442" into the NPO Electronic Sheet/Regional Sheet
- request sample(s) through Notice tool, indicating a single Commercial Product for each request

	rtial Ship: 01 - Price Pol: 05 Status: 01 Canc:
	≿: 0 Sample Type: Sample Non Std Type ▼
	Closing Type: Sample Std Type
	Sample Non Std Type Sample Non Std w Spi Tests
	Lab Sheet:
	A
SO NPO Sample	
N K P 1	9
Header	<i>*</i>
SO Nr: 8018502433	Customer: 99770200 01 ST-TOKYO SO Type: 30 Sample Order Cost Center: JT3129 SAMPLES /SALES
PO Nr.	Carrier Code: 0001 Price Policy: 05 Currency: 02 U.S. DDLLAR V Reg Name:
Notes:	Status: 01 All items pending.m Issuing Date: 25-JUN-2018 Ord Val: 0.0000 Sample Reg Date: 25-Jun-2018
La	
Sch I Nr PO I. Nr. 1.1.10 000001	Finished Good Comm Qty Open Qty Plant Open Qty Req Qty Unit Price RD CD EDD St STM32F429NIH6 30 30 30 0.0000 25 Jun-18 01-Mar-59 01
	51M307423NIH6 30 30 30 30 0.0000 25500-18 01-Mar-53 01-Mar-53 01
•	51M3.07423NIH6 30 30 30 30 0.0000 2350m18 01-Mar-53 01-Mar-53 01
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RER1906 for PCN11442 ST SG8E (Singapore) additional source for STM8L052x, STM8L151x and STM8L152x products

Reliability Evaluation Plan

Oct 09th, 2020

MDG Quality & Reliability Department



RERMCD1906 – F9GO2 Technology Transfer R8 to SG8E (Singapore) STM STM8L Die Test Vehicles

Die Vehicle	Process Perimeter	Assembly Line	Package	Number of Reliability Lots
768	F9GO2	MUAR	LQFP14*14 80L	3 lots to qualify Process Perimeter
764	F9002	JSCC	LQFP7*7 48L	Then 1 lot by Die



RERMCD1906 – F9GO2 Technology Transfer R8 to SG8E (Singapore) STM STM8L Die Reliability Trials

Reliability Trial & Standard		Test Conditions	Pass Criteria	Lot Strategy	Units per Lot
ESD HBM	0060102 JESD22-A114ANSI/ESDA JEDEC JS-001	25°C	2kV (class 2)	1 to 3 lots	3
ESD CDM	ESD Charged Device Model ANSI/ESD STM5.3.1	Aligned with device datasheet	250V to 500V	1 lot	3
LU	0018695 JESD78	125°C REG-ON Configuration 125°C REG-OFF Configuration	No concern	1 to 3 lots	3 3
EDR + Bake	JESD22-A117 JESD22-A103	125°C & 3.6V Cycling 150°C Bake	10k cycles 1500h 1000h	1 to 3 lots 1 st lot 2 nd & 3 rd if any	77
EDR + Bake	JESD22-A117 JESD22-A103	25°C & 3.6V Cycling 150°C Bake	10k cycles 168h	1 to 3 lots	77
EDR + Bake	JESD22-A117 JESD22-A103	-40°C & 3.6V Cycling 150°C Bake	10k cycles 168h	1 to 3 lots	77
ELFR	MIL-STD-883 Method 1005 JESD22-A108 JESD74	125°C & 3.6V	48h	3 lots by process perimeter	500 units min per lot Total of 2000 units
HTOL	MIL-STD-883 Method 1005 JESD22-A108	125°C & 3.6V 100MHz	1200h 600h	1 st lot 2 nd & 3 rd if any	77



RERMCD1906 – F9GO2 Technology Transfer R8 to SG8E (Singapore) STM8L Package Test Vehicles

Package Line	Assembly Line	Package	Wire	Die Vehicle / Rawline (*)	Number of Reliability Lots	
LQFP	MUAR	LQFP14*14 80L	Au	768 / 1S*768		
	JSCC	LQFP7*7 48L	Ag	764 / 5B*764		
	ASE	LQFP7*7 48L	Au	768 / 5B*768	3 lots to qualify F9GO2 Technology	
QFN	JSCC	UFQFPN4*4 28L	Ag	764 / MB*764	Then 1 lot by Package Assembly Line	
WLCSP	SCS	WLCSP32	-	768 / CF*768		



RERMCD1906 – F9GO2 Technology Transfer R8 to SG8E (Singapore) STM STM8L Package Reliability Trials

Reliability Trial & Standard		Test Conditions	Pass Criteria	Lot Strategy	Units per Lot
PC	Pre Conditioning: Moisture Sensitivity Jedec Level 1 J-STD-020/ JESD22-A113 Pre Conditioning: Moisture Sensitivity Jedec Level 3 J-STD-020/ JESD22-A113	Bake (125°C / 24h) Soak (85°C / 85% RH / 168h) for level 1 Convection reflow: 3 passes with Jedec level 1 Bake (125°C / 24h) Soak (30°C / 60% RH / 192h) for level 3 Convection reflow: 3 passes with Jedec level 3	3 Passes MSL1/3	1 to 3 lots	231 to 308 (**)
UHAST (*) (**)	Unbiased Highly Accelerated Temperature & Humidity Stress JESD22-A118	130°C, 85%RH, 2 Atm	96h	1 to 3 lots	77
TC (*)	Thermal Cycling JESD22-A104	-65°C +150°C	500Cy	1 to 3 lots	77
THB (*)	Temperature Humidity Bias JESD22-A101	85°C, 85% RH, bias	1000h	1 to 3 lots	77
HTSL (*)	High Temperature Storage Life JESD22-A103	150°C - no bias	1000h	1 to 3 lots	77
Construction Analysis	JESD22-B102 JESD22-B100/B108	Including Solderability & Physical Dimensions	No concern	1 by package assembly line	15 10
ESD CDM	ESD Charged Device Model ANSI/ESD STM5.3.1	Aligned with device datasheet	250V to 500V	1 by package assembly line	3



(*) Tests performed after preconditioning (**) UHAST not done for BGA

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